

Product / Process Change Notification



N° 2016-051-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of Infineon's Front End Kulim, Malaysia as second source wafer production location affecting the TLx496x Hall Switch Family

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **23. July 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
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► Products affected:

Please refer to attached affected product list 1_cip16051_a



► Detailed Change Information:

Subject: Introduction of Infineon's Front End Kulim, Malaysia as second source wafer production location affecting the TLx496x Hall Switch Family

Reason: Capacity increase and secure supply.

Description:		<u>Old</u>	<u>New</u>
Wafer production location:		<ul style="list-style-type: none"> Infineon Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Regensburg, Germany and Infineon Kulim, Malaysia
Wafer test location:		<ul style="list-style-type: none"> Infineon Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Regensburg, Germany and Infineon Kulim, Malaysia
Wafer dicing location:		<ul style="list-style-type: none"> Infineon Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Regensburg, Germany and Infineon Kulim, Malaysia and Infineon Wuxi, China
Wafer dicing process:		<ul style="list-style-type: none"> Laser stealth dicing 	<ul style="list-style-type: none"> Laser stealth dicing and mechanical dicing, affecting following products only: <ul style="list-style-type: none"> - TLx4963 in SOT23 - TLx4965 in SOT23 - TLE496x in SC59 and PSSO
Final wafer thickness:		<ul style="list-style-type: none"> 150µm 	<ul style="list-style-type: none"> 150µm and 185µm, affecting following products only: <ul style="list-style-type: none"> - TLx4963 in SOT23 - TLx4965 in SOT23 150µm and 210µm, affecting following products only: <ul style="list-style-type: none"> - TLE496x in SC59 and PSSO
Distance between chip and package in data sheet:		Considering 150µm wafer thickness from site Regensburg: <ul style="list-style-type: none"> TLE496x in PSSO: 0.64±0.05 mm TLE496x in SC59: 0.515±0.05 mm TLx4963 and TLx4965 in SOT23: 0.385±0.05 mm 	Considering wafer thicknesses from both production sites: <ul style="list-style-type: none"> TLE496x in PSSO: 0.61±0.08 mm TLE496x in SC59: 0.55±0.09 mm TLx4963 and TLx4965 in SOT23: 0.37±0.07 mm

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► **Product Identification:**

Traceability is ensured by lot number.

► **Impact of Change:**

No change in form, fit and function.
No impact expected on parameters and reliability.

For automotive products only: DeQuMa-ID: SEM-DS-01, SEM-PW-03,
SEM-PW-13, SEM-PA-19 and SEM-TF-01

► **Attachments:**

Affected product list 1_cip16051_a

► **Time Schedule:**

- | | |
|-------------------------------|----------------------|
| ■ Final qualification report: | Available on demand |
| ■ First samples available: | Available on request |
| ■ Intended start of delivery: | 30-November-2019 |

If you have any questions, please do not hesitate to contact your local Sales office.